INSTRUMENTS WITH	CONFIGURABLE V	SINGLE-BIT DUAL-SUPPLY BUS TRANSCEIVE VOLTAGE TRANSLATION AND 3-STATE OUTPUT SCES530D-DECEMBER 2003-REVISED NOVEMBER 20
 Available in the Texas Instrum NanoStar™ and NanoFree™ F Fully Configurable Dual-Rail I Each Port to Operate Over the 3.6-V Power-Supply Range V_{CC} Isolation Feature - If Eithe GND, Both Ports Are in the Hi State DIR Input Circuit Referenced for ±12-mA Output Drive at 3.3 V I/Os Are 4.6-V Tolerant 	Packages Design Allows Full 1.2-V to Pr V _{CC} Input Is at gh-Impedance	 I_{off} Supports Partial-Power-Down Mode Operation Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II ESD Protection Exceeds JESD 22 2000-V Human-Body Model (A114-A) 200-V Machine Model (A115-A) 1000-V Charged-Device Model (C101)
	CCCA 1 6 GND 2 5	E DRL PACKAGE (TOP VIEW) YEP OR YZP PACKAGE (BOTTOM VIEW) VCCB VCCA 1 6 VCCB A 63 46 B DIR GND 2 5 DIR GND 692 56 DIR A 3 4 B 91 669 V _{CCB}
GND 2 5 DIR A 3 4 B See mechanical drawings for dimensions	A 3 4	

DESCRIPTION/ORDERING INFORMATION

This single-bit noninverting bus transceiver uses two separate configurable power-supply rails. The SN74AVC1T45 is optimized to operate with V_{CCA}/V_{CCB} set at 1.4 V to 3.6 V. It is operational with V_{CCA}/V_{CCB} as low as 1.2 V. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

ORDERIN	G INFORMATION
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TA	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
616	<mark>Nano</mark> Star™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP	Topo and roal	SN74AVC1T45YEPR	TO
–40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Tape and reel	SN74AVC1T45YZPR	TC_
	SOT (SOT-23) – DBV	Tape and reel	SN74AVC1T45DBVR	DT1_
	SOT (SC-70) – DCK	Tape and reel	SN74AVC1T45DCKR	TC_
	SOT (SOT-553) – DRL	Reel of 4000	SN74AVC1T45DRLR	UE_

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(2) DBV/DCK/DRL: The actual top-side marking has one additional character that designates the assembly/test site. YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

PDPlease be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. NanoFree are trademarks of Texas Instruments.



SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The SN74AVC1T45 is designed for asynchronous communication between two data buses. The logic levels of the direction-control (DIR) input activate either the B-port outputs or the A-port outputs. The device transmits data from the A bus to the B bus when the B-port outputs are activated and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports always is active and must have a logic HIGH or LOW level applied to prevent excess I_{CC} and I_{CCZ} .

The SN74AVC1T45 is designed so that the DIR input is powered by V_{CCA} .

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

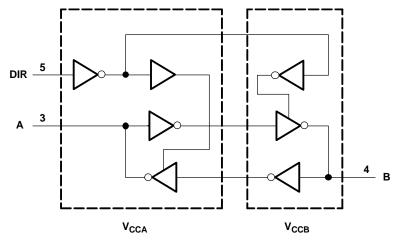
The V_{CC} isolation feature ensures that if either V_{CC} input is at GND, then both ports are in the high-impedance state.

NanoStar[™] and NanoFree[™] package technology is a major breakthrough in IC packaging concepts, using the die as the package.

INPUT DIR	OPERATION
L	B data to A bus
н	A data to B bus

(1) Input circuits of the data I/Os always are active.

LOGIC DIAGRAM (POSITIVE LOGIC)





SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CCA} V _{CCB}	Supply voltage range		-0.5	4.6	V
		I/O ports (A port)	-0.5	4.6	
VI	Input voltage range ⁽²⁾	I/O ports (B port)	-0.5	4.6	V
		Control inputs	-0.5	4.6	
V	Voltage range applied to any output in the high-impedance or	A port	-0.5	4.6	V
Vo	power-off state ⁽²⁾	B port	-0.5	4.6	v
V	Valtere many condicates and extend in the birth on low state $(2)(3)$	A port	-0.5	V _{CCA} + 0.5	V
Vo	Voltage range applied to any output in the high or low state $^{(2)(3)}$	B port	B port -0.5		V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V_{CCA} , V_{CCB} , or GND			±100	mA
		DBV package		165	
0		DCK package		259	°C/W
θ_{JA}	Package thermal impedance ⁽⁴⁾	DRL package		142	-0/00
		YEP/YZP package		123	
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) (4) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current ratings are observed.

The package thermal impedance is calculated in accordance with JESD 51-7.

SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005



Recommended Operating Conditions⁽¹⁾⁽²⁾⁽³⁾

			V _{CCI}	V _{cco}	MIN	MAX	UNIT
V _{CCA}	Supply voltage				1.2	3.6	V
V _{CCB}	Supply voltage				1.2	3.6	V
			1.2 V to 1.95 V		$V_{CCI} imes 0.65$		
V _{IH}	High-level input voltage	Data inputs	1.95 V to 2.7 V		1.6		V
	input voltage		2.7 V to 3.6 V		2		
			1.2 V to 1.95 V			$V_{CCI} imes 0.35$	
V _{IL}	Low-level input voltage	Data inputs	1.95 V to 2.7 V			0.7	V
	input voltage		2.7 V to 3.6 V			0.8	
			1.2 V to 1.95 V		$V_{CCA} imes 0.65$		
VIH	High-level input voltage	DIR (referenced to V _{CCA})	1.95 V to 2.7 V		1.6		V
	input voltage	(Telefeneed to V _{CCA})	2.7 V to 3.6 V		2		
			1.2 V to 1.95 V			$V_{CCA} imes 0.35$	
VIL	Low-level input voltage	DIR (referenced to V _{CCA})	1.95 V to 2.7 V			0.7	V
	input voltage	(Telefeneed to V _{CCA})	2.7 V to 3.6 V			0.8	
VI	Input voltage				0	3.6	V
	O data data literat	Active state			0	V _{cco}	V
Vo	Output voltage	3-state			0	3.6	V
				1.2 V		-3	
				1.4 V to 1.6 V		6	
I _{OH}	High-level output cu	irrent		1.65 V to 1.95 V		-8	mA
				2.3 V to 2.7 V		-9	
				3 V to 3.6 V		-12	
				1.2 V		3	
				1.4 V to 1.6 V		6	
I _{OL}	Low-level output cu	rrent		1.65 V to 1.95 V		8	mA
				2.3 V to 2.7 V		9	
				3 V to 3.6 V		12	
Δt/Δv	Input transition rise	or fall rate				5	ns/V
T _A	Operating free-air te	emperature			-40	85	°C

V_{CCI} is the V_{CC} associated with the input port.
 V_{CCO} is the V_{CC} associated with the output port.
 All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005

Electrical Characteristics⁽¹⁾⁽²⁾

over recommended operating free-air temperature range (unless otherwise noted)

		TEST COND	TIONS	V	M	Т	_A = 25°C	;	–40°C to	85°C	
PARAMETER		TEST COND	TIONS	V _{CCA}	V _{CCB}	MIN	TYP	MAX	MIN	MAX	UNIT
		I _{OH} = -100 μA		1.2 V to 3.6 V	1.2 V to 3.6 V				V _{CCO} - 0.2 V		
		I _{OH} = -3 mA		1.2 V	1.2 V		0.95				
V _{ОН}		I _{OH} =6 mA	$V_{I} = V_{IH}$	1.4 V	1.4 V				1.05		V
011		I _{OH} =8 mA		1.65 V	1.65 V				1.2		
		I _{OH} = -9 mA		2.3 V	2.3 V				1.75		
		I _{OH} = -12 mA		3 V	3 V				2.3		
		I _{OL} = 100 μA		1.2 V to 3.6 V	1.2 V to 3.6 V					0.2	
		I _{OL} = 3 mA		1.2 V	1.2 V		0.15				
V		$I_{OL} = 6 \text{ mA}$	$V_{I} = V_{IL}$	1.4 V	1.4 V					0.35	V
V _{OL}		I _{OL} = 8 mA	$v_{I} = v_{IL}$	1.65 V	1.65 V					0.45	v
		I _{OL} = 9 mA		2.3 V	2.3 V					0.55	
		I _{OL} = 12 mA		3 V	3 V					0.7	
I _I	DIR	$V_I = V_{CCA}$ or GND		1.2 V to 3.6 V	1.2 V to 3.6 V		±0.025	±0.25		±1	μΑ
1	A port	V_1 or $V_0 = 0$ to 3.6	V	0 V	0 to 3.6 V		±0.1	±1		±5	μA
l _{off}	B port	$v_1 \text{ or } v_0 = 0.00 \text{ s.0}$	v	0 to 3.6 V	0 V		±0.1	±1		±5	μA
I _{OZ}	A or B port	$V_{O} = V_{CCO}$ or GNE)	1.2 V to 3.6 V	1.2 V to 3.6 V		±0.5	±2.5		±5	μΑ
				1.2 V to 3.6 V	1.2 V to 3.6 V					10	
I _{CCA}		$V_I = V_{CCI}$ or GND,	$I_{O} = 0$	0 V	3.6 V					-2	μA
				3.6 V	0 V					10	
				1.2 V to 3.6 V	1.2 V to 3.6 V					10	
I _{CCB}		$V_I = V_{CCI}$ or GND,	$I_{O} = 0$	0 V	3.6 V					10	μA
				3.6 V	0 V					-2	
I _{CCA} (see	+ I _{CCB} Table 1)	$V_I = V_{CCI}$ or GND,	$I_{O} = 0$	1.2 V to 3.6 V	1.2 V to 3.6 V					20	μA
C _i	Control inputs	V _I = 3.3 V or GND		3.3 V	3.3 V		2.5				pF
C _{io}	A or B port	$V_{O} = 3.3 \text{ V or GNE}$)	3.3 V	3.3 V		6				pF

 $\begin{array}{ll} \mbox{(1)} & V_{CCO} \mbox{ is the } V_{CC} \mbox{ associated with the output port.} \\ \mbox{(2)} & V_{CCI} \mbox{ is the } V_{CC} \mbox{ associated with the input port.} \end{array}$



SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.2 V (see Figure 1)

	FROM	то	V _{CCB} = 1.2 V	V _{CCB} = 1.5 V	V _{CCB} = 1.8 V	V _{CCB} = 2.5 V	V _{CCB} = 3.3 V	
PARAMETER	(INPUT)	(OUTPUT)	ТҮР	ТҮР	ТҮР	ТҮР	ТҮР	UNIT
t _{PLH}	А	В	3.3	2.7	2.4	2.3	2.4	5
t _{PHL}	A	Б	3.3	2.7	2.4	2.3	2.4	ns
t _{PLH}	В	А	3.3	3.1	2.9	2.8	2.7	20
t _{PHL}	D	A	3.3	3.1	2.9	2.8	2.7	ns
t _{PHZ}	DIR	А	5.1	5.2	5.3	5.2	3.7	20
t _{PLZ}	DIK	A	5.1	5.2	5.3	5.2	3.7	ns
t _{PHZ}	סוס	В	5.3	4.3	4	3.3	3.7	20
t _{PLZ}	DIR	Б	5.3	4.3	4	3.3	3.7	ns
t _{PZH} ⁽¹⁾	DIR	^	8.6	7.3	6.8	6.1	6.4	20
t _{PZL} ⁽¹⁾	DIR	A	8.6	7.3	6.8	6.1	6.4	ns
t _{PZH} ⁽¹⁾	DID	D	8.3	7.8	7.7	7.5	5.8	
t _{PZL} ⁽¹⁾	DIR	В	8.3	7.8	7.7	7.5	5.8	ns

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.5 V \pm 0.1 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO	V _{CCB} = 1.2 V	V _{ССВ} = ± 0.1		V _{ССВ} = ± 0.1		V _{ССВ} = ± 0.2		V _{ССВ} = ± 0.3		UNIT			
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX				
t _{PLH}	А	В	2.9	0.7	5.6	0.6	5.2	0.5	4.2	0.5	3.8	20			
t _{PHL}	A	Б	2.9	0.7	5.6	0.6	5.2	0.5	4.2	0.5	3.8	ns			
t _{PLH}	В	А	2.6	0.6	5.5	0.4	5.3	0.3	4.9	0.3	4.8	20			
t _{PHL}	D	A	2.6	0.6	5.5	0.4	5.3	0.3	4.9	0.3	4.8	ns			
t _{PHZ}	DIR	А	3.8	1.6	6.7	1.5	6.8	0.3	6.9	0.9	6.9	20			
t _{PLZ}	DIK	A	3.8	1.6	6.7	1.5	6.8	0.3	6.9	0.9	6.9	ns			
t _{PHZ}	DIR	В	5.1	1.8	8.1	1.6	7.1	1.1	4.7	1.4	4.5	20			
t _{PLZ}	DIK	Б	5.1	1.8	8.1	1.6	7.1	1.1	4.7	1.4	4.5	ns			
t _{PZH} ⁽¹⁾	DID	•	7.7		13.6		12.4		9.6		9.3				
t _{PZL} ⁽¹⁾	DIR	DIR	DIR	DIR	A	7.7		13.6		12.4		9.6		9.3	ns
t _{PZH} ⁽¹⁾	DIR	DIR	Р	6.7		12.3		12		11.1		10.7	20		
t _{PZL} ⁽¹⁾			В	6.7		12.3		12		11.1		10.7	ns		

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.



SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.8 V \pm 0.15 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{CCB} = ± 0.1		V _{ССВ} = ± 0.1		V _{ССВ} = ± 0.2		V _{CCB} = ± 0.3		UNIT		
		(001F01)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX			
t _{PLH}	А	В	2.7	0.6	5.3	0.5	5	0.4	3.9	0.4	3.4	20		
t _{PHL}	A	D	2.7	0.6	5.3	0.5	5	0.4	3.9	0.4	3.4	ns		
t _{PLH}	В	А	2.3	0.5	5.2	0.4	5	0.3	4.6	0.2	4.4	20		
t _{PHL}	D	A	2.3	0.5	5.2	0.4	5	0.3	4.6	0.2	4.4	ns		
t _{PHZ}	DIR	А	3.8	1.6	5.9	1.6	5.9	1.6	5.9	0.5	6	20		
t _{PLZ}	DIR	A	3.8	1.6	5.9	1.6	5.9	1.6	5.9	0.5	6	ns		
t _{PHZ}	DIR	В	5	1.8	7.7	1.4	6.8	1	4.4	1.4	5.3	20		
t _{PLZ}	DIR	D	5	1.8	7.7	1.4	6.8	1	4.4	1.4	5.3	ns		
t _{PZH} ⁽¹⁾		•	7.3		12.9		11.8		9		8.7	20		
t _{PZL} ⁽¹⁾	DIR	DIR	DIR	DIR A	7.3		12.9		11.8		9		8.7	ns
t _{PZH} ⁽¹⁾	סוס	В	6.5		11.2		10.9		9.8		9.4	20		
t _{PZL} ⁽¹⁾	DIR	В	6.5		11.2		10.9		9.8		9.4	ns		

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 2.5 V \pm 0.2 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{CCB} = ± 0.1	1.5 V I V	V _{CCB} = ± 0.1		V _{ССВ} = ± 0.2		V _{ССВ} = ± 0.3		UNIT		
	(INPUT)	(001P01)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX			
t _{PLH}	А	В	2.6	0.5	4.9	0.4	4.6	0.3	3.4	0.3	3	20		
t _{PHL}	A	Б	2.6	0.5	4.9	0.4	4.6	0.3	3.4	0.3	3	ns		
t _{PLH}	В	А	2.2	0.4	4.2	0.3	3.8	0.2	3.4	0.2	3.3	20		
t _{PHL}	Б	A	2.2	0.4	4.2	0.3	3.8	0.2	3.4	0.2	3.3	ns		
t _{PHZ}	DID	А	2.8	0.3	3.8	0.8	3.8	0.4	3.8	0.5	3.8	20		
t _{PLZ}	DIR	A	2.8	0.3	3.8	0.8	3.8	0.4	3.8	0.5	3.8	ns		
t _{PHZ}	DIR	В	4.9	2	7.6	1.5	6.5	0.6	4.1	1	4	20		
t _{PLZ}	DIK	Б	4.9	2	7.6	1.5	6.5	0.6	4.1	1	4	ns		
t _{PZH} ⁽¹⁾		^	7.1		11.8		10.3		7.5		7.3	20		
t _{PZL} ⁽¹⁾	DIR	DIR	DIR	DIR A	7.1		11.8		10.3		7.5		7.3	ns
t _{PZH} ⁽¹⁾	DIR	В	5.4		8.6		8.1		7		6.6	20		
t _{PZL} ⁽¹⁾	DIR	В	5.4		8.6		8.1		7		6.6	ns		

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.



SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{CCB} = ± 0.1		V _{ССВ} = ± 0.1		V _{CCB} = ± 0.2		V _{ССВ} = ± 0.3		UNIT				
	(INFUT)	(001201)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX					
t _{PLH}	٨	В	2.6	0.4	4.7	0.3	4.4	0.2	3.3	0.2	2.8	~~				
t _{PHL}	A	Б	2.6	0.4	4.7	0.3	4.4	0.2	3.3	0.2	2.8	ns				
t _{PLH}	В	А	2.2	0.4	3.8	0.3	3.4	0.2	3	0.1	2.8					
t _{PHL}	Б	A	2.2	0.4	3.8	0.3	3.4	0.2	3	0.1	2.8	ns				
t _{PHZ}	DIR	А	3.1	1.3	4.3	1.3	4.3	1.3	4.3	1.3	4.3					
t _{PLZ}	DIR	A	3.1	1.3	4.3	1.3	4.3	1.3	4.3	1.3	4.3	ns				
t _{PHZ}	DIR	В	4	0.7	7.4	0.6	6.5	0.7	4	1.5	4.9					
t _{PLZ}	DIR	Б	4	0.7	7.4	0.6	6.5	0.7	4	1.5	4.9	ns				
t _{PZH} ⁽¹⁾		^	6.2		11.2		9.9		7		6.7					
t _{PZL} ⁽¹⁾	DIR	DIR	DIR	DIR	DIR	A	6.2		11.2		9.9		7		6.7	ns
t _{PZH} ⁽¹⁾	DIR	DID	DIR	DID	חוח	P	5.7		8.9		8.5		7.2		6.8	
t _{PZL} ⁽¹⁾		В	5.7		8.9		8.5		7.2		6.8	ns				

(1) The enable time is a calculated value, derived using the formula shown in the enable times section.

Operating Characteristics

 $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	$V_{CCA} =$ $V_{CCB} = 1.2 V$	V _{CCA} = V _{CCB} = 1.5 V	V _{CCA} = V _{CCB} = 1.8 V	$V_{CCA} = V_{CCB} = 2.5 V$	$V_{CCA} = V_{CCB} = 3.3 V$	UNIT	
			TYP	TYP	TYP	TYP	TYP		
A-port input, B-port output		C _L = 0 pF, f = 10 MHz,	3	3	3	3	4	~	
C _{pdA} ⁽¹⁾	B-port input, A-port output	$t_r = t_f = 1 \text{ ns}$	13	13	14	15	15	pF	
C _{pdB} ⁽¹⁾	A-port input, B-port output	C _L = 0 pF, f = 10 MHz,	13	13	14	15	15	pF	
	B-port input, A-port output	$t_r = t_f = 1 \text{ ns}$	3	3	3	3	3	рг	

(1) Power dissipation capacitance per transceiver



SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005

Power-Up Considerations

A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies. To guard against such power-up problems, take the following precautions:

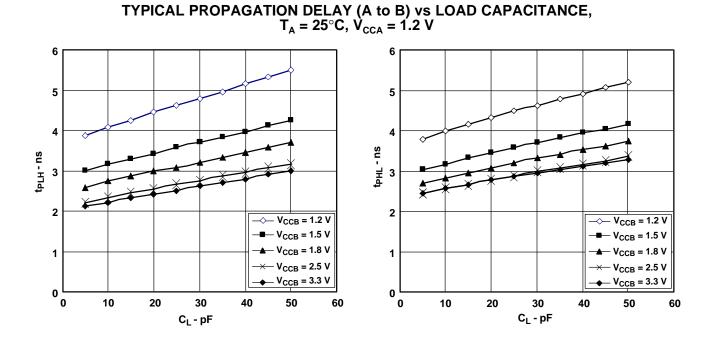
- 1. Connect ground before any supply voltage is applied.
- 2. Power up V_{CCA}.
- 3. V_{CCB} can be ramped up along with or after V_{CCA} .

v	V _{CCA}									
V _{CCB}	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	UNIT			
0 V	0	<0.5	<0.5	<0.5	<0.5	<0.5				
1.2 V	<0.5	<1	<1	<1	<1	1				
1.5 V	<0.5	<1	<1	<1	<1	1				
1.8 V	<0.5	<1	<1	<1	<1	<1	μΑ			
2.5 V	<0.5	1	<1	<1	<1	<1				
3.3 V	<0.5	1	<1	<1	<1	<1				

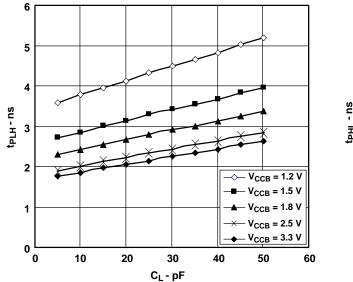
Table 1. Typical Total Static Power Consumption (I_{CCA} + I_{CCB})

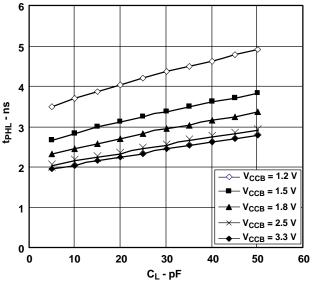
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TYPICAL CHARACTERISTICS



TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE, $T_{\rm A}$ = 25°C, $V_{\rm CCA}$ = 1.5 V





TEXAS STRUMENTS

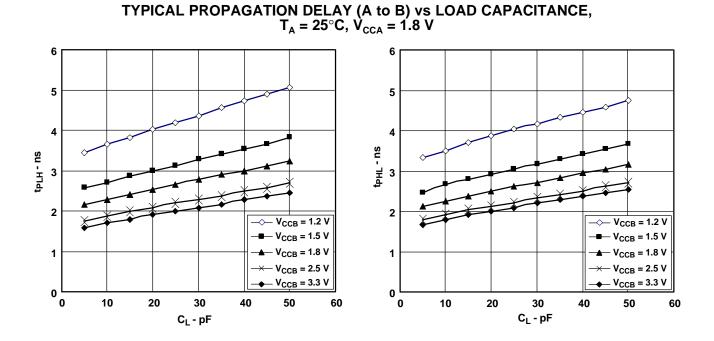
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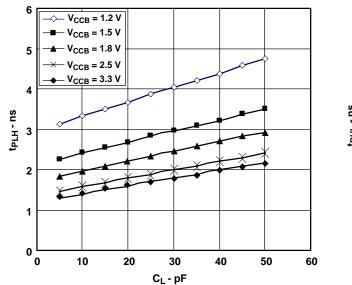
SN74AVC1T45 SINGLE-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

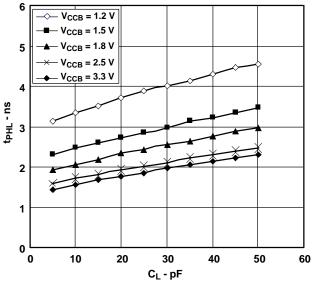
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TYPICAL CHARACTERISTICS



TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE, $T_{\rm A}$ = 25°C, $V_{\rm CCA}$ = 2.5 V



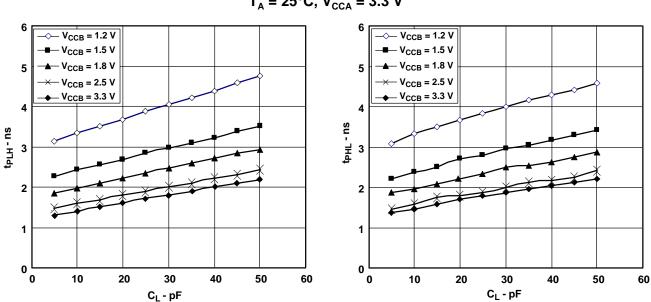


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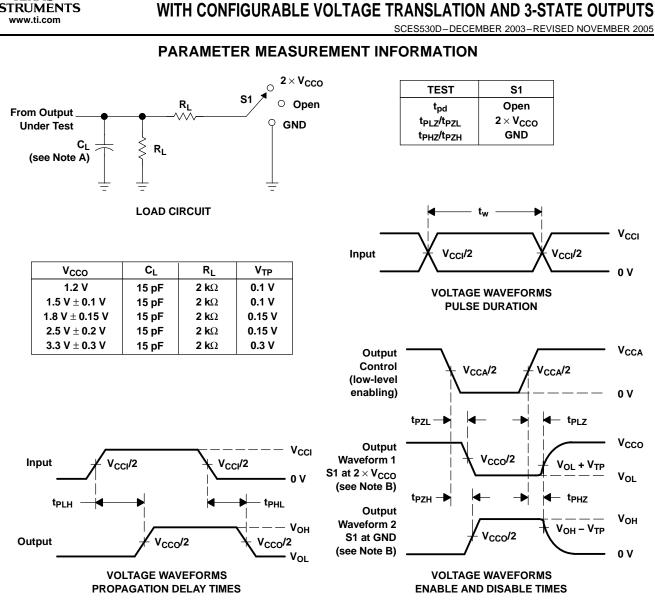


SCES530D-DECEMBER 2003-REVISED NOVEMBER 2005

TYPICAL CHARACTERISTICS



TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE, $T_{\rm A}$ = 25°C, $V_{\rm CCA}$ = 3.3 V



Texas

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: $PRR \le 10$ MHz, $Z_0 = 50 \Omega$, $dv/dt \ge 1$ V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. V_{CCI} is the V_{CC} associated with the input port.
- I. V_{CCO} is the V_{CC} associated with the output port.

Figure 1. Load Circuit and Voltage Waveforms

SN74AVC1T45

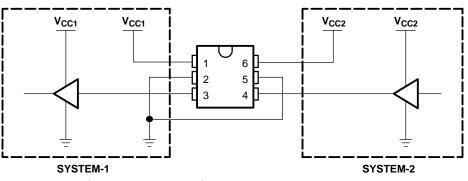
SINGLE-BIT DUAL-SUPPLY BUS TRANSCEIVER



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APPLICATION INFORMATION

Figure 2 shows an example of the SN74AVC1T45 being used in a unidirectional logic level-shifting application.



PIN	NAME	FUNCTION	DESCRIPTION			
1	V _{CCA}	V _{CC1}	SYSTEM-1 supply voltage (1.2 V to 3.6 V)			
2	GND	GND	Device GND			
3	A	OUT	Output level depends on V _{CC1} voltage.			
4	В	IN	Input threshold value depends on V _{CC2} voltage.			
5	DIR	DIR	GND (low level) determines B-port to A-port direction.			
6	V _{CCB}	V _{CC2}	SYSTEM-2 supply voltage (1.2 V to 3.6 V)			

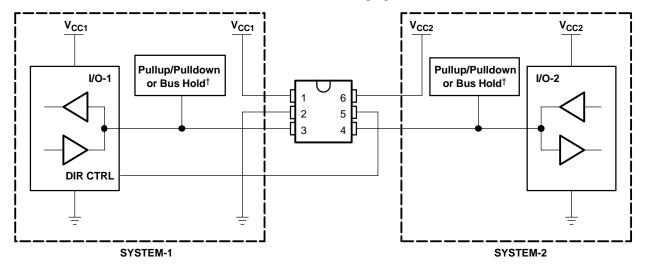
Figure 2. Unidirectional Logic Level-Shifting Application

SN74AVC1T45 SINGLE-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

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APPLICATION INFORMATION

Figure 3 shows the SN74AVC1T45 being used in a bidirectional logic level-shifting application. Since the SN74AVC1T45 does not have an output-enable (OE) pin, the system designer should take precautions to avoid bus contention between SYSTEM-1 and SYSTEM-2 when changing directions.



The following table shows data transmission from SYSTEM-1 to SYSTEM-2 and then from SYSTEM-2 to SYSTEM-1.

STATE	DIR CTRL	I/O-1	I/O-2	DESCRIPTION
1	Н	Out	In	SYSTEM-1 data to SYSTEM-2
2	Н	Hi-Z	Hi-Z	SYSTEM-2 is getting ready to send data to SYSTEM-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on pullup or pulldown. ⁽¹⁾
3	L	Hi-Z	Hi-Z	DIR bit is flipped. I/O-1 and I/O-2 still are disabled. The bus-line state depends on pullup or pulldown. ⁽¹⁾
4	L	Out	In	SYSTEM-2 data to SYSTEM-1

(1) SYSTEM-1 and SYSTEM-2 must use the same conditions, i.e., both pullup or both pulldown.

Figure 3. Bidirectional Logic Level-Shifting Application

Enable Times

Calculate the enable times for the SN74AVC1T45 using the following formulas:

- t_{PZH} (DIR to A) = t_{PLZ} (DIR to B) + t_{PLH} (B to A)
- t_{PZL} (DIR to A) = t_{PHZ} (DIR to B) + t_{PHL} (B to A)
- t_{PZH} (DIR to B) = t_{PLZ} (DIR to A) + t_{PLH} (A to B)
- t_{PZL} (DIR to B) = t_{PHZ} (DIR to A) + t_{PHL} (A to B)

In a bidirectional application, these enable times provide the maximum delay from the time the DIR bit is switched until an output is expected. For example, if the SN74AVC1T45 initially is transmitting from A to B, then the DIR bit is switched; the B port of the device must be disabled before presenting it with an input. After the B port has been disabled, an input signal applied to it appears on the corresponding A port after the specified propagation delay.



PACKAGE OPTION ADDENDUM

4-Nov-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AVC1T45DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC1T45DBVRE4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC1T45DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC1T45DBVTE4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC1T45DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC1T45DCKRE4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC1T45DCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC1T45DCKTE4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC1T45DRLR	ACTIVE	SOP	DRL	6	4000	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM
SN74AVC1T45YEPR	ACTIVE	WCSP	YEP	6	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74AVC1T45YZPR	ACTIVE	WCSP	YZP	6	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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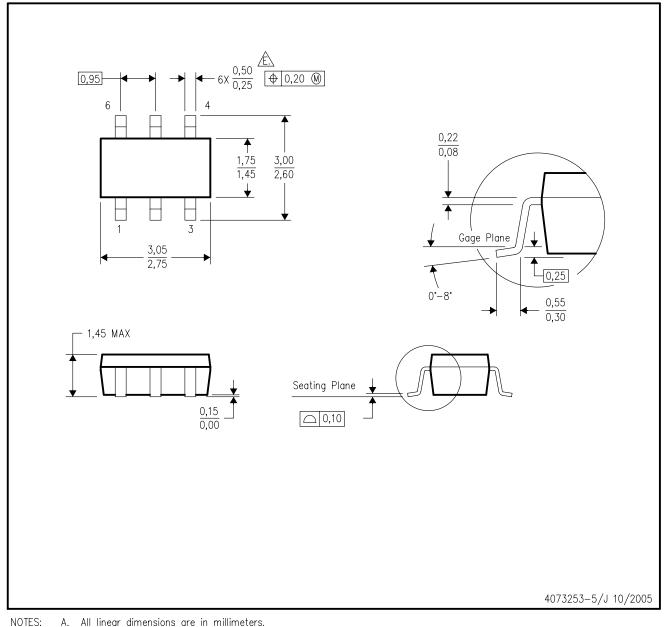
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



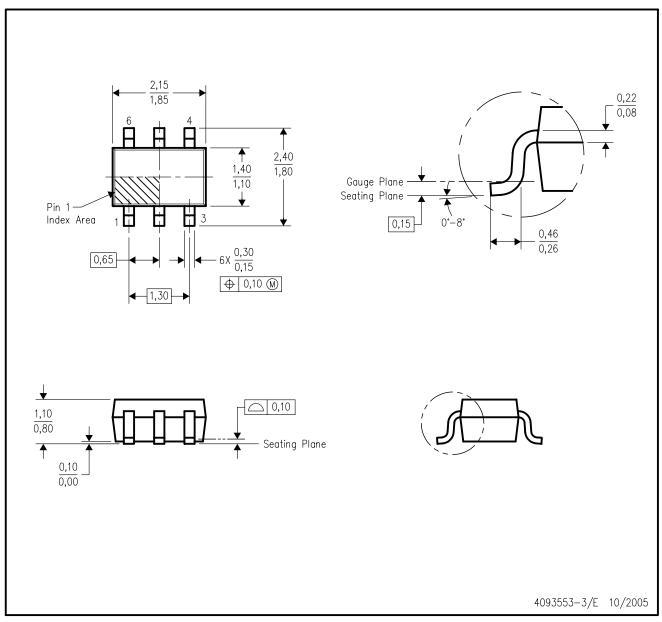
A. All linear dimensions are in millimeters.

- This drawing is subject to change without notice. Β.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation. C.
- D.
- E Falls within JEDEC MO-178 Variation AB, except minimum lead width.



DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



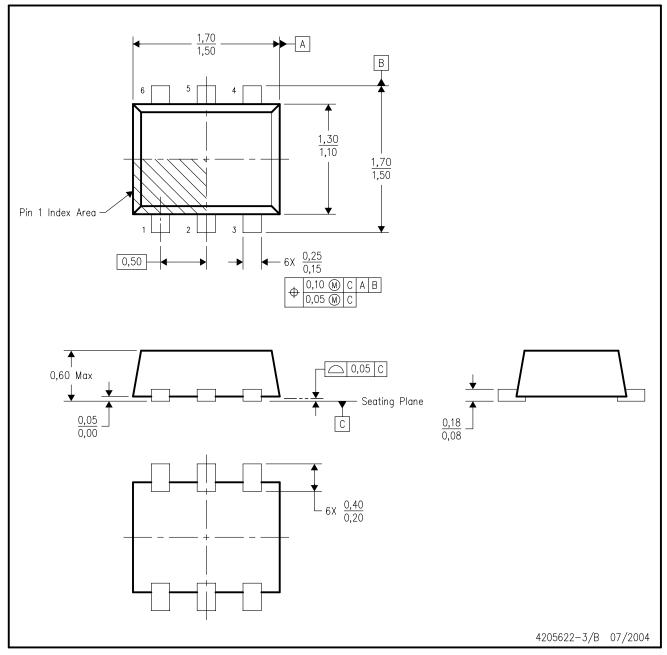
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



DRL (R-PDSO-N6)

PLASTIC SMALL OUTLINE



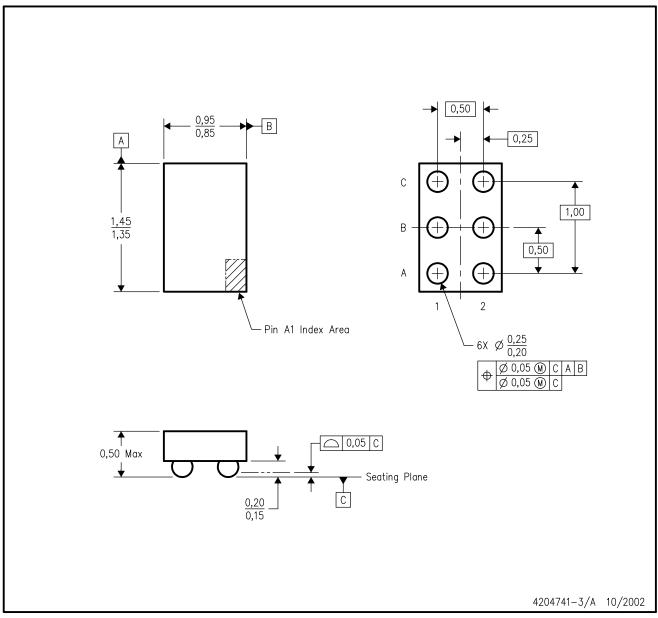
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. JEDEC package registration is pending.



YZP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



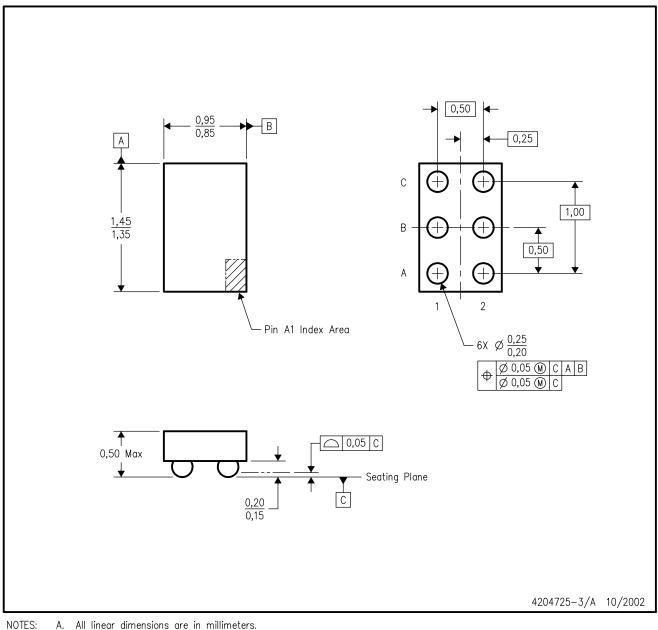
NOTES:

- A. All linear dimensions are in millimeters.B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 6 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

YEP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES:

- This drawing is subject to change without notice. Β.
- C. NanoStar™ package configuration.
- D. This package is tin-lead (SnPb). Refer to the 6 YZP package (drawing 4204741) for lead-free.

NanoStar is a trademark of Texas Instruments.

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